

ABSTRACT

POLISHING APPARATUS AND POLISHING METHOD

5 The present invention relates to a polishing apparatus and a polishing method for
polishing a substrate while detecting a film thickness of the substrate by analyzing
reflected light from the substrate on a polishing pad. The polishing apparatus includes a
polishing table (3) configured to support a polishing pad (2) having a through-hole (61); a
pad-height measuring device (32) configured to measure a height of the polishing surface
10 (2a); a pure-water supply line (63) and a pure-water suction line(64) coupled to the
through-hole (61) ; a flow-rate adjusting device (71) coupled to the pure-water supply line
(63); and an operation controller (35) configured to control an operation of the flow-rate
adjusting device (71). The operation controller (35) determines a flow rate of the pure
water corresponding to a measured value of the height of the polishing surface (2a) from
15 correlation data, and controls the operation of the flow-rate adjusting device (71) such
that the pure water flows through the pure-water supply line (63) at the determined flow
rate.

Figure 1